

PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT OF ASSIGNOR'S INTEREST

CONVEYING PARTY DATA

Name	Execution Date
Jun Kaneko	2002-02-19
Naoki Nagano	2002-03-27
Satoru Kamoto	2002-02-20
Katsushi Fujii	2002-03-31
Mayumi Shinoda	2002-02-25
Atsushi Fuse	2002-02-26
Michinari Kohno	2002-02-27

RECEIVING PARTY DATA

Name	Street Address	Internal Address	City	State/Country	Postal Code
Sony Corporation	7-35, Kitashingawa 6-chome	Shinagawa-Ku	Tokyo	JP	141-0001

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number	11252171

CORRESPONDENCE DATA

FAX NUMBER: (908) 654-0415
Correspondence will be sent via US Mail when the fax attempt is unsuccessful.

When the customer number has been provided, the Office of Public Records will obtain the correspondence data from the official record on file at the USPTO.

CUSTOMER NUMBER: 000530

NAME OF PERSON SIGNING:	Robert B. Cohen
DATE SIGNED:	2006-06-01

Total Attachments: 3
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 source=SONYJP949-usassn-A000002.tif

CH \$40.00 121095 11252171

ASSIGNMENT

WHEREAS, I, as a below named inventor, residing at the address stated next to my name, am a sole inventor (if only one name is listed below) or a joint inventor (if plural names are listed below) of certain new and useful improvements in DATA PROVIDING SYSTEM, DATA PROVIDING APPARATUS AND METHOD, DATA ACQUISITION SYSTEM AND METHOD, AND PROGRAM STORAGE MEDIUM for which application for Letters Patent of the United States of America was executed by me on the date indicated next to my name and address;

AND WHEREAS, Sony Corporation, a Japanese corporation with offices at 6-7-35 Kitashinagawa, Shinagawa-Ku, Tokyo, Japan (hereinafter referenced as ASSIGNEE) are desirous of acquiring all interest in, to and under said invention, said application disclosing the invention and in, to and under any Letters Patent or similar legal protection which may be granted therefor in the United States and in any and all foreign countries;

NOW THEREFORE, in consideration of the sum of One Dollar (\$1.00), and other good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged, I, as a sole or joint inventor as indicated below, by these presents do hereby assign, sell and transfer unto the said ASSIGNEE, its successors, assigns, and legal representatives, the entire right, title and interest in the said invention, said application, including any divisions and continuations thereof, and in and to any and all Letters Patent of the United States, and countries foreign thereto, which may be granted for said invention, and in and to any and all priority rights and/or convention rights under the International Convention for the Protection of Industrial Property, Inter-American Convention Relating to Patents, Designs and Industrial Models, and any other international agreements to which the United States of America adheres, and to any other benefits accruing or to accrue to me with respect to the filing of applications for patents or securing of patents in the United States and countries foreign thereto, and I hereby authorize and request the Commissioner of Patents to issue the said United States Letters Patent to said ASSIGNEE, as the assignee of the whole right, title and interest thereto;

And I further agree to execute all necessary or desirable and lawful future documents, including assignments in favor of ASSIGNEE or its designee, as ASSIGNEE or its successors, assigns and legal representatives may from time-to-time present to me and without further remuneration, in order to perfect title in said invention, modifications, and improvements in said invention, applications and Letters Patent of the United States and countries foreign thereof;

And I further agree to properly execute and deliver and without further remuneration, such necessary or desirable and lawful papers for application for foreign patents, for filing subdivisions of said application for patent, and or, for obtaining any reissue or reissues of any Letters Patent which may be granted for my aforesaid invention, as the ASSIGNEE thereof shall hereafter require and prepare at its own expense;

And I further agree that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said application, said invention and said Letters Patent and legal equivalents in foreign countries as may be known and accessible to me and will testify as to the same in any interference or litigation related thereof;

And I hereby covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment and sale.

And I hereby authorize and request my attorney(s) of record in this application to insert the serial number and filing date of this application in the spaces that follow: Serial Number 10/017,369, Filing Date 12/14/01

S01P1867US00

This assignment executed on the dates indicated below.

Jun Kaneko

Name of first or sole inventor

Execution date of U.S. Patent Application

Kanagawa, Japan

Residence of first or sole inventor

Jun Kaneko
Signature of first or sole inventor

Feb. 19, 2002
Date of this assignment

Naoki Nagano

Name of second inventor

Execution date of U.S. Patent Application

Tokyo, Japan

Residence of second inventor

Naoki Nagano
Signature of second inventor

March 27, 2002
Date of this assignment

Satoru Kamoto

Name of third inventor

Execution date of U.S. Patent Application

Kanagawa, Japan

Residence of third inventor

Satoru Kamoto
Signature of third inventor

Feb. 20, 2002
Date of this assignment

Katsushi Fujii

Name of fourth inventor

Execution date of U.S. Patent Application

Chiba, Japan

Residence of fourth inventor

Katsushi Fujii
Signature of fourth inventor

March 31, 2002
Date of this assignment

Mayumi Shinoda

Name of fifth inventor

Execution date of U.S. Patent Application

Kanagawa, Japan

Residence of fifth inventor

Mayumi Shinoda
Signature of fifth inventor

Feb. 25, 2002
Date of this assignment

Atsushi Fuse

Name of sixth inventor

Execution date of U.S. Patent Application

Tokyo, Japan

Residence of sixth inventor

Atsushi Fuse

Feb 26, 2002

Signature of sixth inventor

Date of this assignment

Michinari Kohno

Name of seventh inventor

Execution date of U.S. Patent Application

Kanagawa, Japan

Residence of seventh inventor

Michinari Kohno

Feb. 27, 2002

Signature of seventh inventor

Date of this assignment